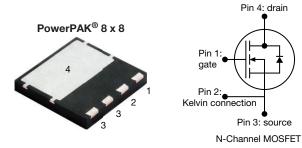


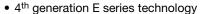


## **E Series Power MOSFET**



PRODUCT SUMMAR	Y	
V <sub>DS</sub> (V) at T <sub>J</sub> max.	65	50
R <sub>DS(on)</sub> typ. (Ω) at 25 °C	V <sub>GS</sub> = 10 V	0.070
Q <sub>g</sub> max. (nC)	6	3
Q <sub>gs</sub> (nC)	1	9
Q <sub>gd</sub> (nC)	1	0
Configuration	Sin	gle

#### **FEATURES**







• Reduced switching and conduction losses



 Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>



### **APPLICATIONS**

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK 8 x 8
Lead (Pb)-free and halogen-free	SIHH080N60E-T1-GE3

ABSOLUTE MAXIMUM RATINGS	(T <sub>C</sub> = 25 °C, un	less otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			$V_{DS}$	600	V
Gate-source voltage			$V_{GS}$	± 30	7 °
Continuous dusin surrent (T. 150 °C)	\/ at 10 \/	T <sub>C</sub> = 25 °C	- I <sub>D</sub>	32	A
Continuous drain current (T <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C		20	
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	96	
Linear derating factor				1.47	W/°C
Single pulse avalanche energy b			E <sub>AS</sub>	226	mJ
Maximum power dissipation			P <sub>D</sub>	184	W
Operating junction and storage temperature range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C
Drain-source voltage slope $T_J = 125  ^{\circ}\text{C}$			dv/dt	100	V/ns
Reverse diode dv/dt <sup>d</sup>	uv/at	10	V/IIS		

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b.  $V_{DD}$  = 120 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_g$  = 25  $\Omega$ ,  $I_{AS}$  = 4.0 A
- c. 1.6 mm from case
- d.  $I_{SD} \le I_D$ , di/dt = 100 A/ $\mu$ s, starting  $T_J$  = 25 °C



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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	$R_{thJA}$	39	51	°C/W	
Maximum junction-to-case (drain)	$R_{thJC}$	0.51	0.68	C/VV	

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V <sub>DS</sub>	V <sub>GS</sub> =	= 0 V, I <sub>D</sub> = 250 μA	600	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I <sub>D</sub> = 1 mA	-	0.64	-	V/°C
Gate-source threshold voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	· V <sub>GS</sub> , I <sub>D</sub> = 250 μA	3.0	-	5.0	V
Onto anima lankana		,	$V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA
Gate-source leakage	I <sub>GSS</sub>	,	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
7		V <sub>DS</sub> =	$V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V}$		-	1	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 480 V	, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	10	μA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 17 A	-	0.070	0.080	Ω
Forward transconductance a	9 <sub>fs</sub>	V <sub>DS</sub>	= 20 V, I <sub>D</sub> = 17 A	-	4.6	-	S
Dynamic							
Input capacitance	C <sub>iss</sub>		V <sub>GS</sub> = 0 V,	-	2557	-	
Output capacitance	C <sub>oss</sub>	,	$V_{DS} = 100 \text{ V},$	-	105	-	
Reverse transfer capacitance	C <sub>rss</sub>		f = 1 MHz	-	6	-	1
Effective output capacitance, energy related <sup>a</sup>	C <sub>o(er)</sub>	V <sub>DS</sub> = 0 V to 480 V, V <sub>GS</sub> = 0 V		-	79	-	pF
Effective output capacitance, time related <sup>b</sup>	C <sub>o(tr)</sub>			-	499	-	
Total gate charge	Qg			-	42	63	
Gate-source charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$I_D = 17 \text{ A}, V_{DS} = 480 \text{ V}$	-	19	-	nC
Gate-drain charge	Q <sub>gd</sub>	7		-	10	-	
Turn-on delay time	t <sub>d(on)</sub>			-	31	62	
Rise time	t <sub>r</sub>	$V_{DD} = 480 \text{ V}, I_D = 17 \text{ A},$		-	96	144	
Turn-off delay time	t <sub>d(off)</sub>	V <sub>GS</sub> =	$=$ 10 V, R <sub>g</sub> = 9.1 $\Omega$	-	37	74	ns
Fall time	t <sub>f</sub>			-	31	62	
Gate input resistance	$R_g$		f = 1 MHz	0.3	0.7	1.4	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	I <sub>S</sub>	showing the	MOSFET symbol showing the		-	35	
Pulsed diode forward current	I <sub>SM</sub>	integral reverse p - n junction diode		-	-	96	- A
Diode forward voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C	C, I <sub>S</sub> = 17 A, V <sub>GS</sub> = 0 V	-	-	1.2	V
Reverse recovery time	t <sub>rr</sub>			-	441	882	ns
Reverse recovery charge	Q <sub>rr</sub>		$5 ^{\circ}\text{C},  I_F = I_S = 17 \text{A},$	-	5.2	10.4	μC
Reverse recovery current	I <sub>RRM</sub>	u/at =	80 A/ $\mu$ s, V <sub>R</sub> = 25 V	-	21	-	A

#### Notes

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$
- $b. \ \ C_{oss(tr)} \ is \ a \ fixed \ capacitance \ that \ gives \ the \ same \ charging \ time \ as \ C_{oss} \ while \ V_{DS} \ is \ rising \ from \ 0 \ \% \ to \ 80 \ \% \ V_{DSS} \ decreases \ d$



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

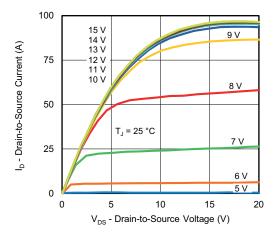


Fig. 1 - Typical Output Characteristics

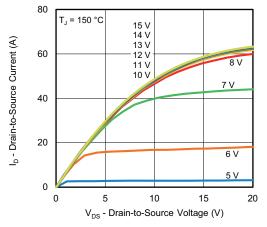


Fig. 2 - Typical Output Characteristics

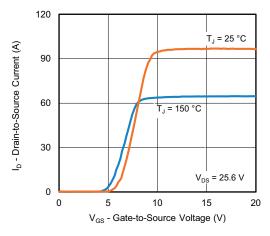


Fig. 3 - Typical Transfer Characteristics

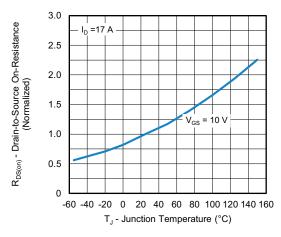


Fig. 4 - Normalized On-Resistance vs. Temperature

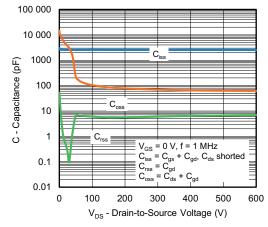


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

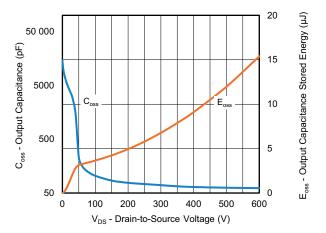


Fig. 6 -  $C_{oss}$  and  $E_{oss}$  vs.  $V_{DS}$ 



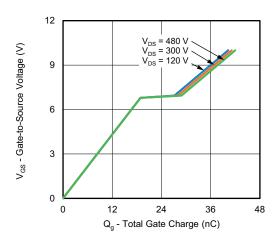


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

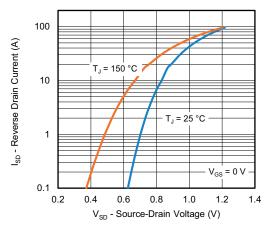


Fig. 8 - Typical Source-Drain Diode Forward Voltage

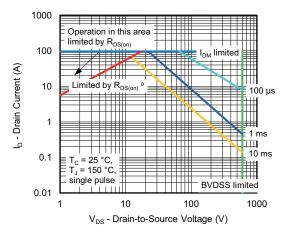


Fig. 9 - Maximum Safe Operating Area



a.  $V_{GS} > minimum \ V_{GS}$  at which  $R_{DS(on)}$  is specified

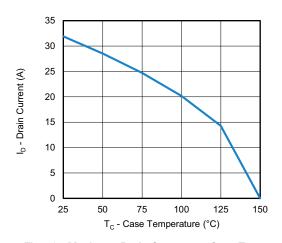


Fig. 10 - Maximum Drain Current vs. Case Temperature

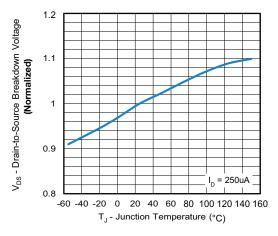


Fig. 11 - Temperature vs. Drain-to-Source Voltage



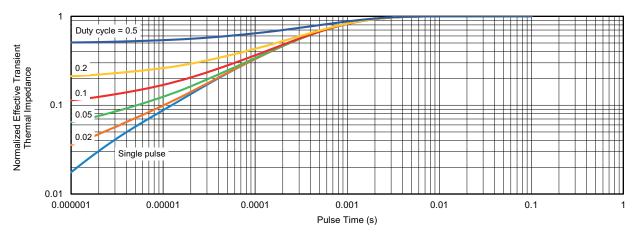


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

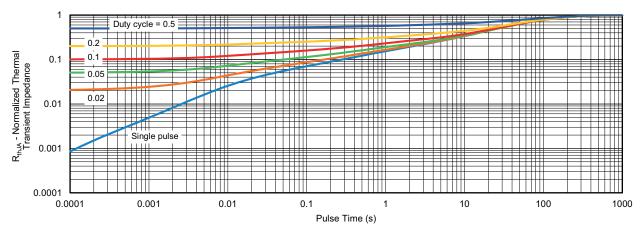


Fig. 13 - Normalized Transient Thermal Impedance, Junction-to-Ambient

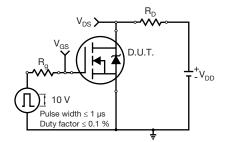


Fig. 14 - Switching Time Test Circuit

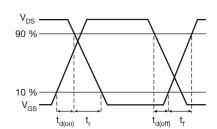


Fig. 15 - Switching Time Waveforms



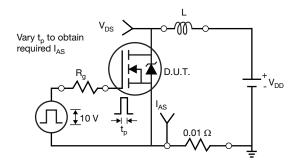


Fig. 16 - Unclamped Inductive Test Circuit

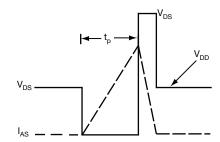


Fig. 17 - Unclamped Inductive Waveforms

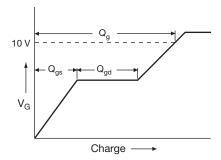


Fig. 18 - Basic Gate Charge Waveform

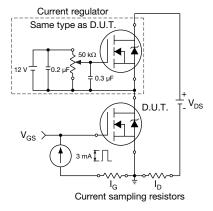
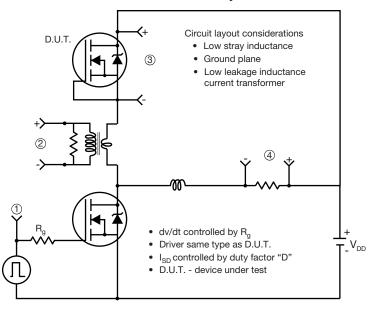


Fig. 19 - Gate Charge Test Circuit



#### Peak Diode Recovery dv/dt Test Circuit



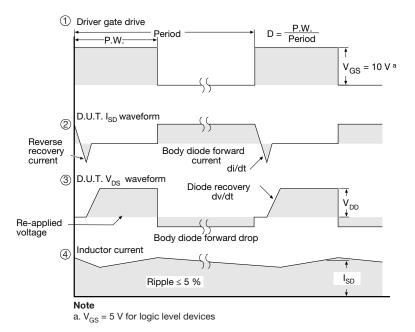


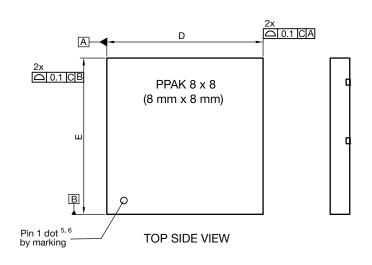
Fig. 20 - For N-Channel

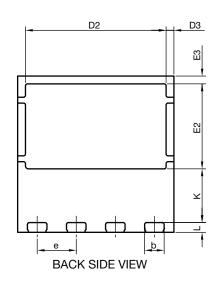
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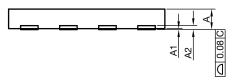


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# PowerPAK® 8 x 8 Case Outline







DIM.	MILLIMETERS		INCHES				
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
Α	0.95	1.00	1.05	0.037	0.039	0.041	
A1	0.00	-	0.05	0.000	-	0.002	
A2	020 ref.				0.008 ref.		
b	0.95	1.00	1.05	0.037	0.039	0.041	
D	7.90	8.00	8.10	0.311	0.315	0.319	
D2	7.10	7.20	7.30	0.280	0.283	0.287	
D3	0.40 BSC			0.016 BSC			
е	2.00 BSC		0.079 BSC				
E	7.90	8.00	8.10	0.311	0.315	0.319	
E2	4.30	4.35	4.40	0.169	0.171	0.173	
E3	0.40 BSC			0.40 BSC 0.016 BSC			
K	2.75 BSC		0.108 BSC				
L	0.45	0.50	0.55	0.018	0.020	0.022	
N <sup>(3)</sup>	8			8 8			

#### Notes

- (1) Use millimeters as the primary measurement
- (2) Dimensioning and tolerances conform to ASME Y14.5 M 1994
- (3) N is the number of terminals
- (4) The pin 1 identifier must be existed on the top surface of the package by using indentation mark or other feature of package body
- (5) Exact shape and size of this feature is optional

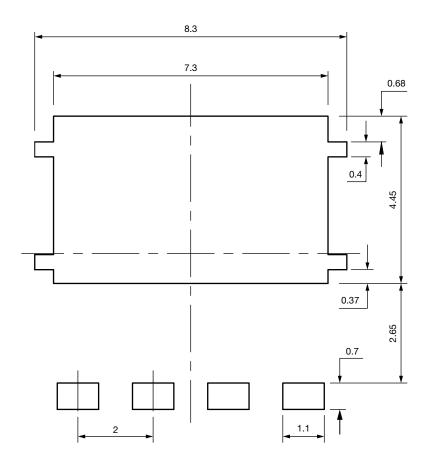
ECN: E20-0518-Rev. B, 28-Sep-2020

DWG: 6041

Revision: 28-Sep-2020 1 Document Number: 67859



# Recommended Minimum PADs for PowerPAK® 8 mm x 8 mm



Dimensions in millimeters



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